

2SK3069

Silicon N Channel MOS FET High Speed Power Switching

REJ03G1062-1100

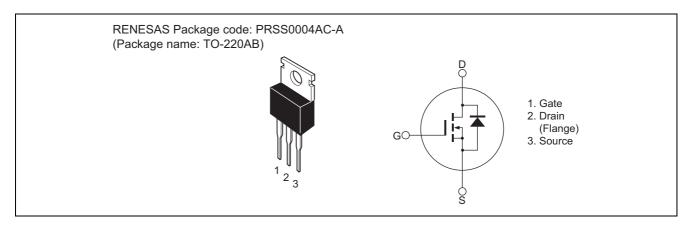
(Previous: ADE-208-694I)

Rev.11.00 Sep 07, 2005

Features

- Low on-resistance $R_{DS(on)} = 6 \text{ m}\Omega \text{ typ.}$
- Low drive current
- 4 V gate drive device can be driven from 5 V source

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	60	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	75	Α
Drain peak current	I _{D(pulse)} Note 1	300	Α
Body-drain diode reverse drain current	I _{DR}	75	Α
Avalanche current	I _{AP} Note 3	50	Α
Avalanche energy	E _{AR} Note 3	214	mJ
Channel dissipation	Pch Note 2	100	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. $PW \le 10\mu s$, duty cycle ≤ 1 %

2. Value at Tc = 25°C

3. Value at Tch = 25°C, Rg \geq 50 Ω

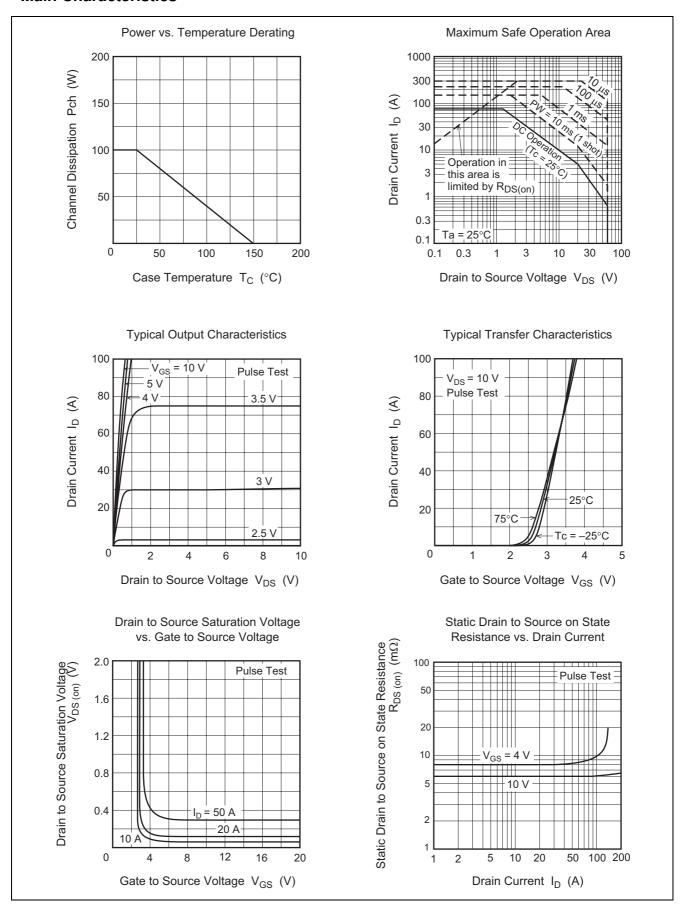
Electrical Characteristics

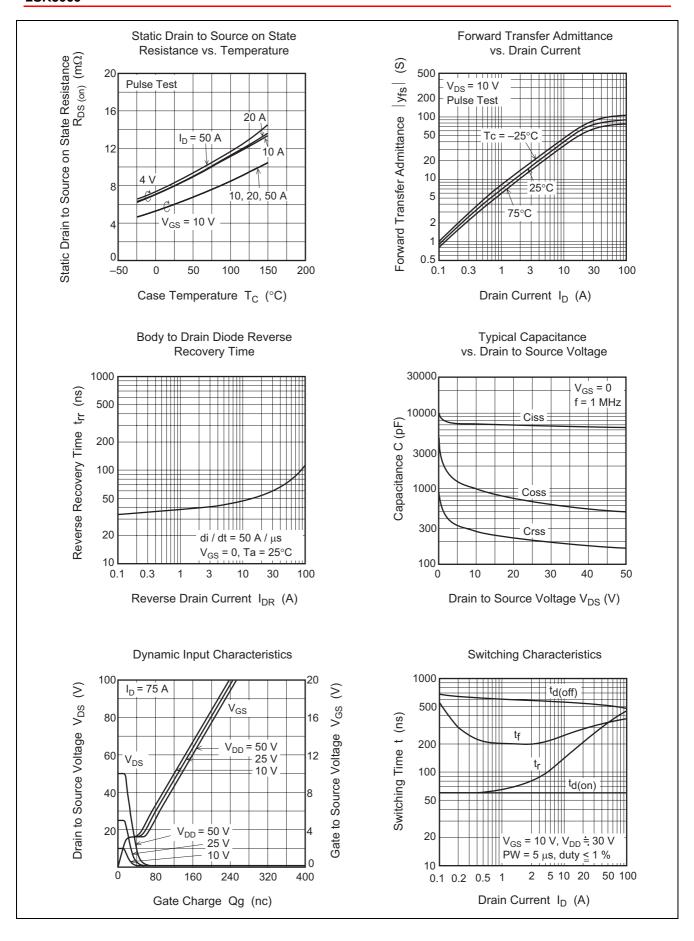
 $(Ta = 25^{\circ}C)$

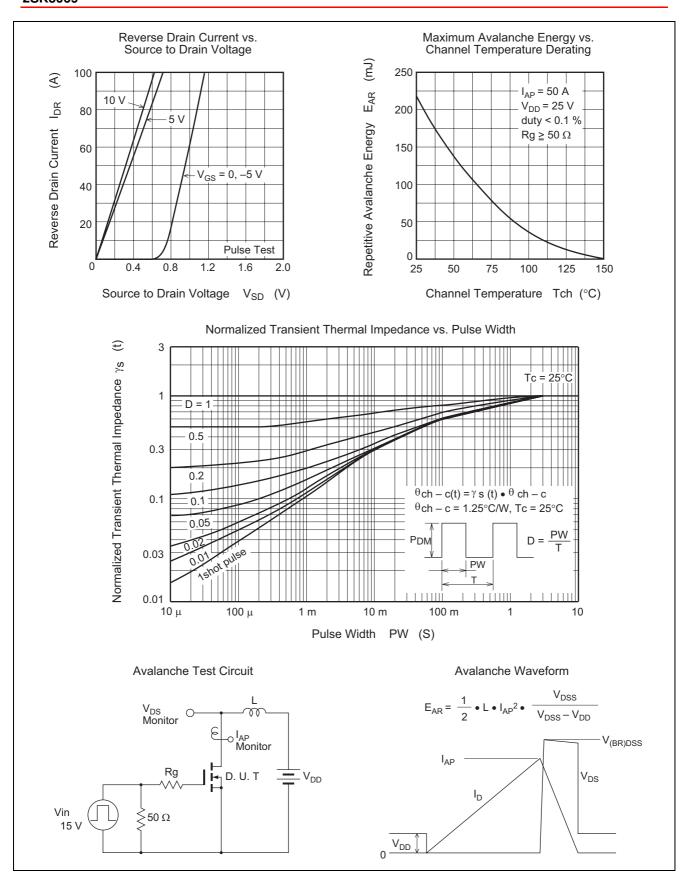
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	60	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±0.1	μΑ	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	10	μΑ	$V_{DS} = 60 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	_	2.5	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}^{\text{Note 4}}$
Static drain to source on state	R _{DS(on)}	_	6.0	7.5	mΩ	$I_D = 40 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note 4}}$
resistance		_	8.0	12	mΩ	$I_D = 40 \text{ A}, V_{GS} = 4 \text{ V}^{\text{Note 4}}$
Forward transfer admittance	y _{fs}	50	80	_	S	$I_D = 40 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note 4}}$
Input capacitance	Ciss	_	7100	_	рF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	1000	_	рF	f = 1 MHz
Reverse transfer capacitance	Crss	_	280	_	рF]
Total gate charge	Qg	_	125	_	nC	$V_{DD} = 25 \text{ V}, V_{GS} = 10 \text{ V},$
Gate to source charge	Qgs	_	25	_	nC	$I_{D} = 75 \text{ A}$
Gate to drain charge	Qgd	_	25	_	nC]
Turn-on delay time	t _{d(on)}	_	60	_	ns	$V_{GS} = 10 \text{ V}, I_D = 40 \text{ A},$
Rise time	t _r	_	300	_	ns	$R_L = 0.75 \Omega$
Turn-off delay time	$t_{d(off)}$	_	520	_	ns]
Fall time	t _f	_	330	_	ns]
Body-drain diode forward voltage	V_{DF}	_	1.05	_	V	$I_F = 75A, V_{GS} = 0$
Body-drain diode reverse recovery time	t _{rr}	_	90	_	ns	$I_F = 75A$, $V_{GS} = 0$ $di_F/dt = 50 A/ \mu s$

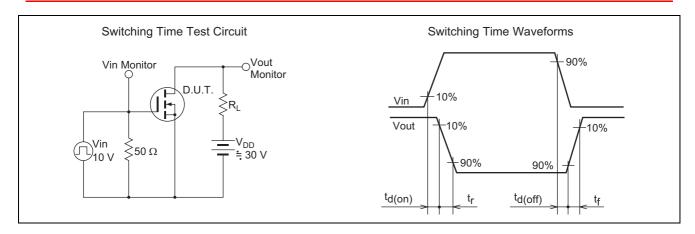
Note: 4. Pulse test

Main Characteristics

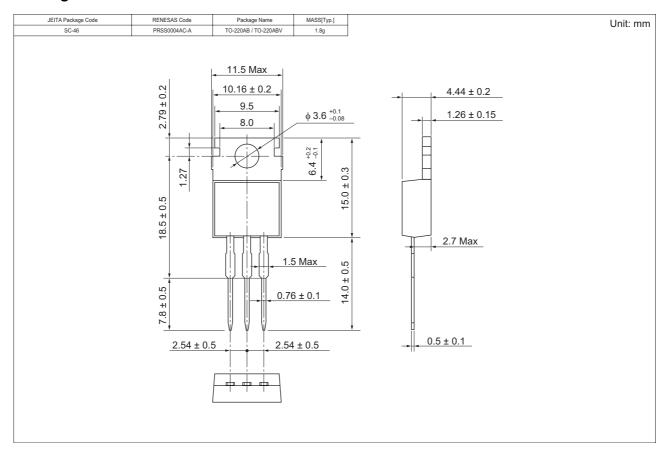








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK3069-E	500 pcs	Box (Sack)

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